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Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	2.5mm +/-0.20mm
B	0.6mm +/-0.35mm

  

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	390 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3300 pF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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